PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Akihiro KOMORI	04/17/2008
Susumu TAKATSUKA	05/01/2008
Toru SASAKI	04/30/2008
Yuichi SAKAI	05/07/2008
Yoichiro SAKO	06/18/2008
Toshiro TERAUCHI	05/29/2008
Hirofumi TAMORI	05/09/2008
Makoto INOUE	05/12/2008
Katsuya SHIRAI	05/13/2008
Motoyuki TAKAI	05/15/2008
Kenichi MAKINO	05/16/2008
Takatoshi NAKAMURA	05/17/2008
Akane SANO	06/24/2008

RECEIVING PARTY DATA

Name:	SONY CORPORATION
Street Address:	1-7-1 Konan, Minato-Ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	108-0075

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12160217

CORRESPONDENCE DATA

Fax Number: (703)413-2220
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
Phone: (703) 413-3000

OP $40.00 12160217

Email: Ldjeudjang@oblon.com
Correspondent Name: Oblon, Spivak, et al.
Address Line 1: 1940 Duke Street
Address Line 4: Alexandria, VIRGINIA 22314

ATTORNEY DOCKET NUMBER:	320664US8PCT
NAME OF SUBMITTER:	Leonie Djeudjang

Total Attachments: 3
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S07P0056US00

Docket Number: 320664US8PCT

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

CONTENT REPRODUCING APPARATUS AND REPRODUCING METHOD

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-Ku, Tokyo, 108-0075 Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar ($1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 12/160,217
Filing Date: July 8, 2008

This assignment executed on the dates indicated below.

Akihiro KOMORI	April 17 . 2008
Name of first or sole inventor	Execution date of U.S. Patent Application
Tokyo, Japan	
Residence of first or sole inventor	
Akihiro Komori	April 17 . 2008
Signature of first or sole inventor	Date of this assignment

S07 P0056US0

Susumu TAKATSUKA 7/5/08
Name of second inventor Execution date of U.S. Patent Application

Tokyo, Japan
Residence of second inventor

Susumu Takatsuka 7/5/08
Signature of second inventor Date of this assignment

Toru SASAKI April 30. 2008
Name of third inventor Execution date of U.S. Patent Application

Tokyo, Japan
Residence of third inventor

Toru Sasaki April 30. 2008
Signature of third inventor Date of this assignment

~~Yuichi Sakai~~ May 7, 2008 YS
Yuichi SAKAI May 7, 2008
Name of fourth inventor Execution date of U.S. Patent Application

Kanagawa, Japan
Residence of fourth inventor

Yuichi Sakai May 7, 2008
Signature of fourth inventor Date of this assignment

Yoichiro SAKO June 18, 2008
Name of fifth inventor Execution date of U.S. Patent Application

Tokyo, Japan
Residence of fifth inventor

Yoichiro Sako June 18, 2008
Signature of fifth inventor Date of this assignment

Toshiro TERAUCHI May 29, 2008
Name of sixth inventor Execution date of U.S. Patent Application

Tokyo, Japan
Residence of sixth inventor

May 29, 2008
Signature of sixth inventor Date of this assignment

Hirofumi TAMORI May 9, 2008
Name of seventh inventor Execution date of U.S. Patent Application

Tokyo, Japan
Residence of seventh inventor

May 9, 2008
Signature of seventh inventor Date of this assignment

S07P0056US00

Makoto INOUE May 12, 2008
Name of eighth inventor Execution date of U.S. Patent Application

Tokyo, Japan
Residence of eighth inventor

Makoto Inoue May 12, 2008
Signature of eighth inventor Date of this assignment

Katsuya SHIRAI May 13, 2008
Name of ninth inventor Execution date of U.S. Patent Application

Kanagawa, Japan
Residence of ninth inventor

Katsuya Shirai May 13, 2008
Signature of ninth inventor Date of this assignment

Motoyuki TAKAI May 15, 2008
Name of tenth inventor Execution date of U.S. Patent Application

Tokyo, Japan
Residence of tenth inventor

Motoyuki Takai May 15, 2008
Signature of tenth inventor Date of this assignment

Kenichi MAKINO May 15, 2008
Name of eleventh inventor Execution date of U.S. Patent Application

Kanagawa, Japan
Residence of eleventh inventor

Kenichi Makino May 16, 2008
Signature of eleventh inventor Date of this assignment

Takatoshi NAKAMURA
Name of twelfth inventor Execution date of U.S. Patent Application

Kanagawa, Japan
Residence of twelfth inventor

Takatoshi Nakamura May 17. 2008
Signature of twelfth inventor Date of this assignment

Akane SANO
Name of thirteenth inventor Execution date of U.S. Patent Application

Tokyo, Japan
Residence of thirteenth inventor

Akane Sano June 24, 2008
Signature of thirteenth inventor Date of this assignment